



8-11 May 2011 - Naples, Italy

SPI 2011



jointly organized by:
University of Cassino, Italy
University of Naples "Federico II", Italy
University of Naples "Parthenope", Italy

supported by:
CREATE Consortium, Naples



15th IEEE Workshop on Signal Propagation on Interconnects

WEBSITE

<http://www.spi2011.unina.it/>

RUN

8-11 May, 2011

VENUE

Conference Center Federico II
Via Partenope 36, 80125 Naples, Italy

DEADLINES

Submission of two or four page manuscript:
by February 15th, 2011

Notification of acceptance:
by March 31st, 2011

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PENDING SPONSORSHIP BY

IEEE - EMC
Electromagnetic Compatibility Society



15th IEEE Workshop on SIGNAL PROPAGATION ON INTERCONNECTS

CALL FOR PAPERS

During the last fourteen years, the IEEE Workshop on Signal Propagation on Interconnects has been developed into a **forum of exchange** where world class developers and researchers will share and discuss leading edge results in the field of interconnect modeling, simulation and measurement at chip, board, and package level. The workshop is also meant **to bring together developers and researchers from industry and academia.**

In view of the last years success, the Committee is looking forward to the **15th Edition**, convened at the **Conference Center Federico II** located on the Naples waterfront: an ideal location with superb views of the gulf, the old harbor, Dell'Ovo Castle and the Vesuvio.

The symposium will include both oral and poster sessions. A number of prominent experts will be giving **tutorials on areas of emerging interest.**

TOPICS

- High-speed Interconnects
- Power Distribution Networks
- Electronic packages and microsystems
- Optical Interconnects
- RF, Microwave and Wireless Interconnects
- Nano-Interconnects and nano-Packages
- Electromagnetic Theory and Modeling
- Transmission Line Theory and Modeling
- Macro-Modeling, reduced-order models
- Advanced Simulation Tools for Modeling Interconnects Structures
- Signal Integrity on High-Speed Interconnects
- Power Integrity/ Ground Noise
- Electromagnetic Compatibility
- Coupling Effects on Interconnects
- Radiation & Interference
- Substrate Effects
- Testing & Interconnects
- Frequency Domain Measurement Techniques
- Time Domain Measurement Techniques

WORKSHOP STANDING COMMITTEE

- **Uwe Arz**, Physikalisch-Technische Bundesanstalt, Braunschweig (GER)
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